

**AMENDMENT TO THE SPECIFICATION**

Page 9, lines 21-30 (last paragraph on Page 9), please substitute the attached paragraph for the corresponding paragraph in the specification:

The solder joints formed in this manner are nevertheless not strong enough to endure subsequent stresses in normal use. To increase the integrity of the bonds, encapsulation is preferred. This can be accomplished by applying a liquid underfill encapsulant to the gap between the detector and interposer after assembly, followed by curing, as is known in the art. However, unlike the prior art, it is necessary to employ an especially designed encapsulating resin that completely cures at a temperature not exceeding 120 degrees C, and preferably much lower. Alternately, the preferred approach is to employ an encapsulating polymer flux that cures at the same time that the solder is reflowed. Such fluxes are described in US Pat 5,985,043 and 6,017,634, which are incorporated herein in their entirety. Such prior art fluxes can be formulated to provide the necessary flux activity at low melting point solder temperatures and also cure fully at about 90 degrees C.